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**VE320 – Summer 2021**

**Introduction to Semiconductor Devices**

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**Chapter 9 Metal-Semiconductor Schottky Junction**



# Outline

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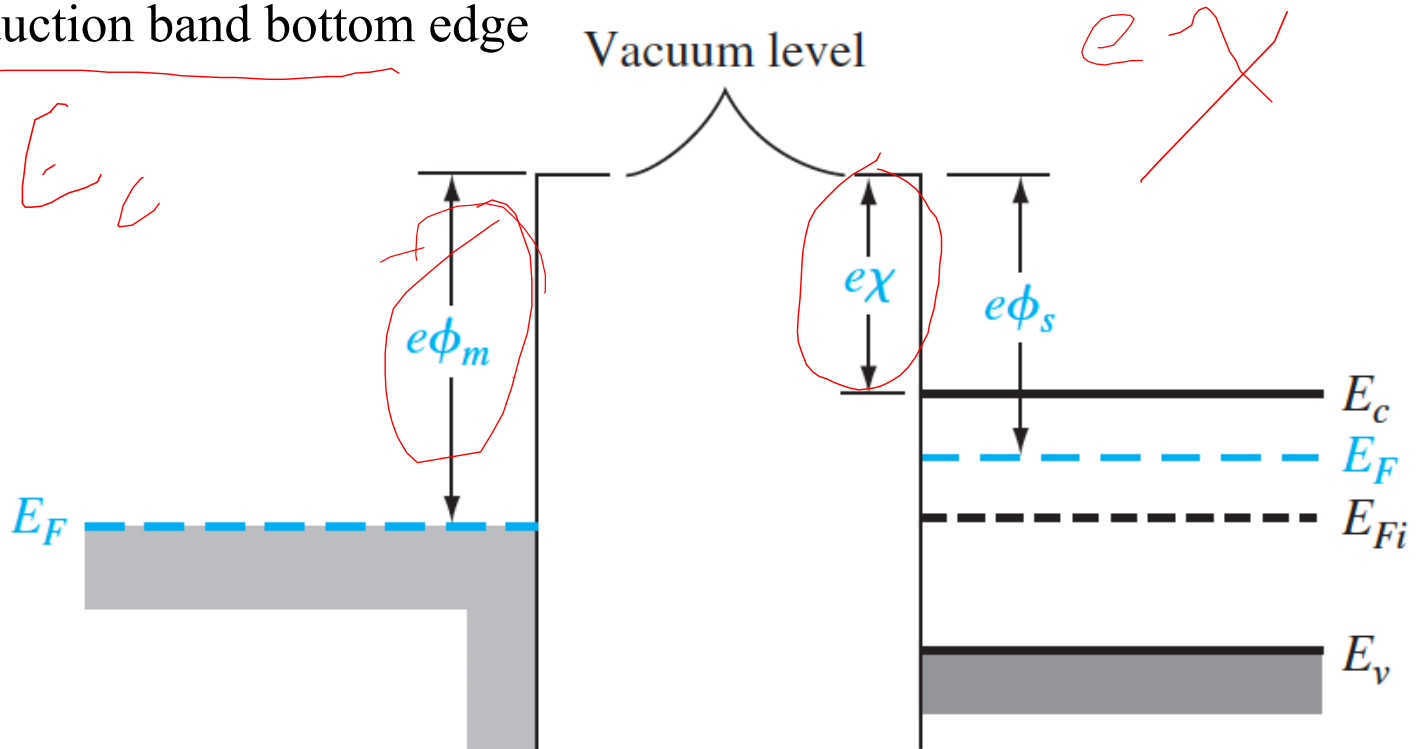
## 9.1 The Schottky barrier diode

## 9.2 Metal-semiconductor Ohmic contacts

# 9.1 The Schottky barrier diode

## Qualitative characteristics

- Work function: energy difference between the vacuum energy level and the Fermi level
- Electron affinity: energy difference between the vacuum energy level and conduction band bottom edge



# 9.1 The Schottky barrier diode

## Qualitative characteristics

Element	Work function, $\phi_m$
Ag, silver	4.26
Al, aluminum	4.28
Au, gold	5.1
Cr, chromium	4.5
Mo, molybdenum	4.6
Ni, nickel	5.15
Pd, palladium	5.12
Pt, platinum	5.65
Ti, titanium	4.33
W, tungsten	4.55

Element	Electron affinity, $\chi$
Ge, germanium	4.13
Si, silicon	4.01
GaAs, gallium arsenide	4.07
AlAs, aluminum arsenide	3.5

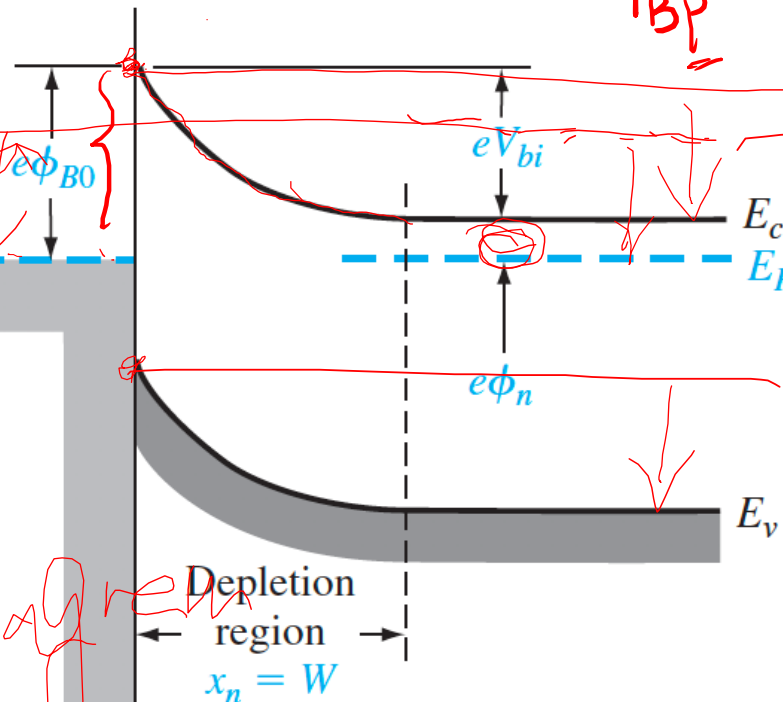
# 9.1 The Schottky barrier diode

## Qualitative characteristics

- Schottky barrier:  $\phi_{B0} = (\phi_m - \chi)$
- Built-in potential barrier:  $V_{bi} = \phi_{B0} - \phi_n$

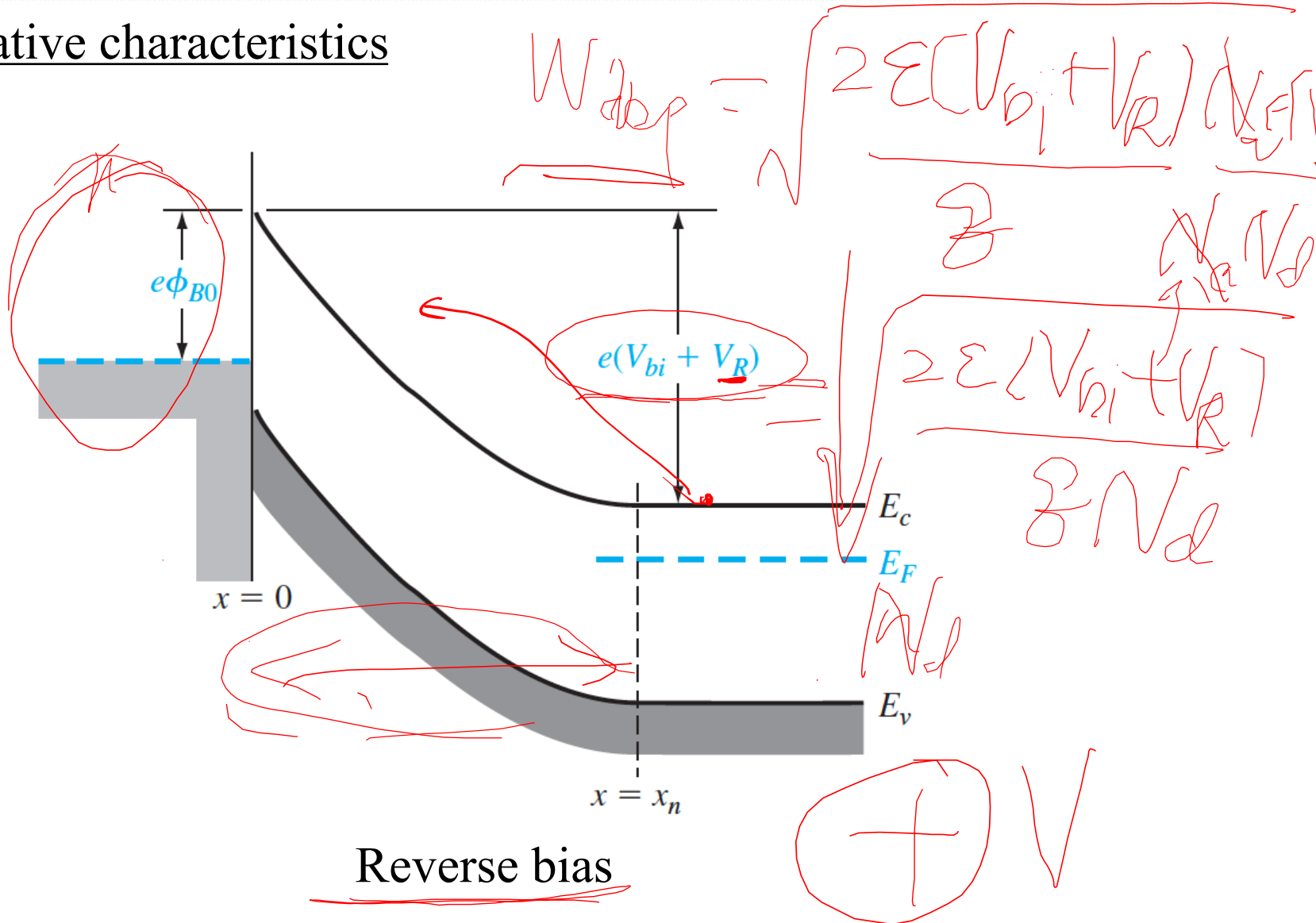
$V_{bi} = \phi_s - \phi_m$

③ plot energy band diagram



# 9.1 The Schottky barrier diode

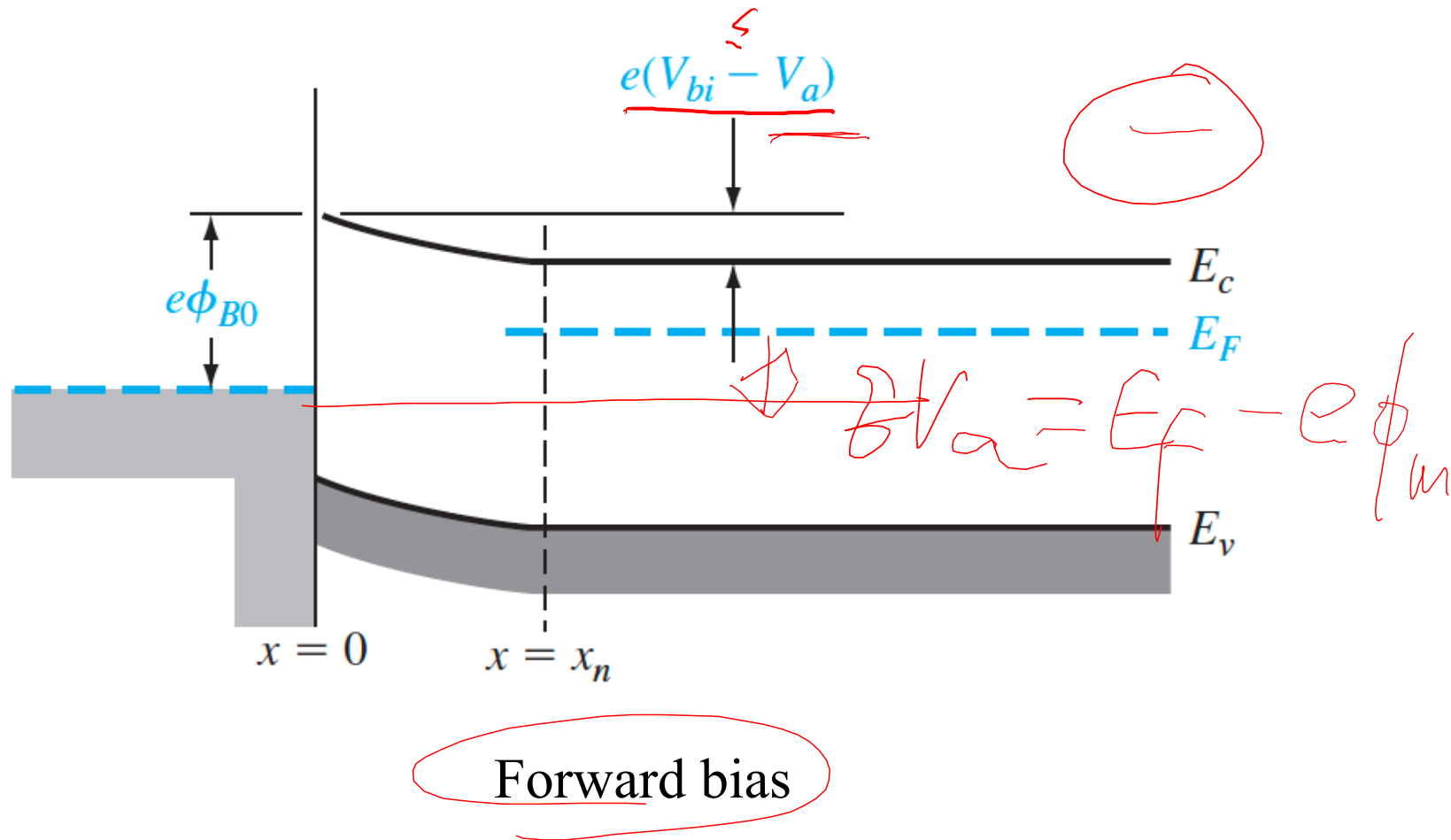
## Qualitative characteristics



Reverse bias

# 9.1 The Schottky barrier diode

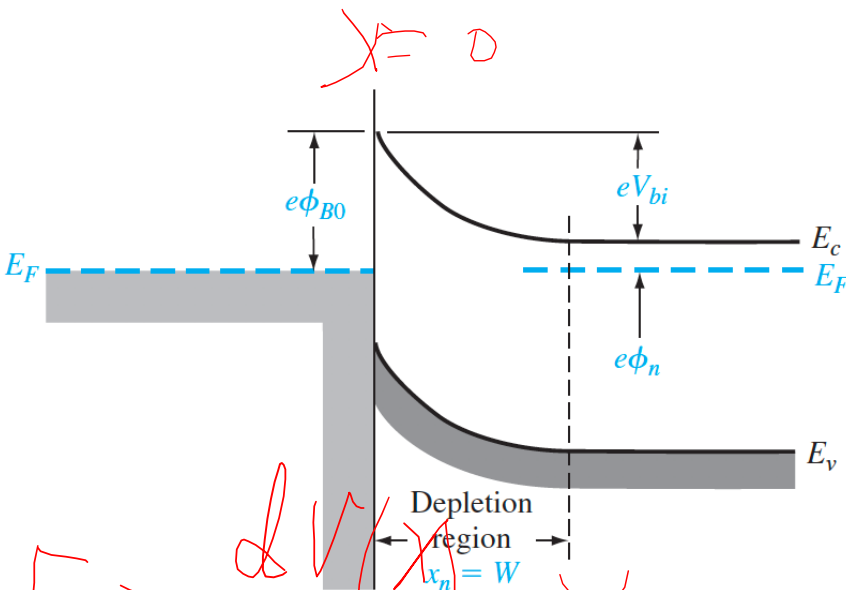
## Qualitative characteristics



# 9.1 The Schottky barrier diode

## Ideal junction properties (electric field)

electrostatic



$$E = \int \frac{eN_d}{\epsilon_s} dx$$

$$= \frac{eN_d}{\epsilon_s} x + C_1$$

$$E(x_n) = 0 \quad eN_d x_n$$

$$C_1 = - \frac{eN_d x_n}{\epsilon_s}$$

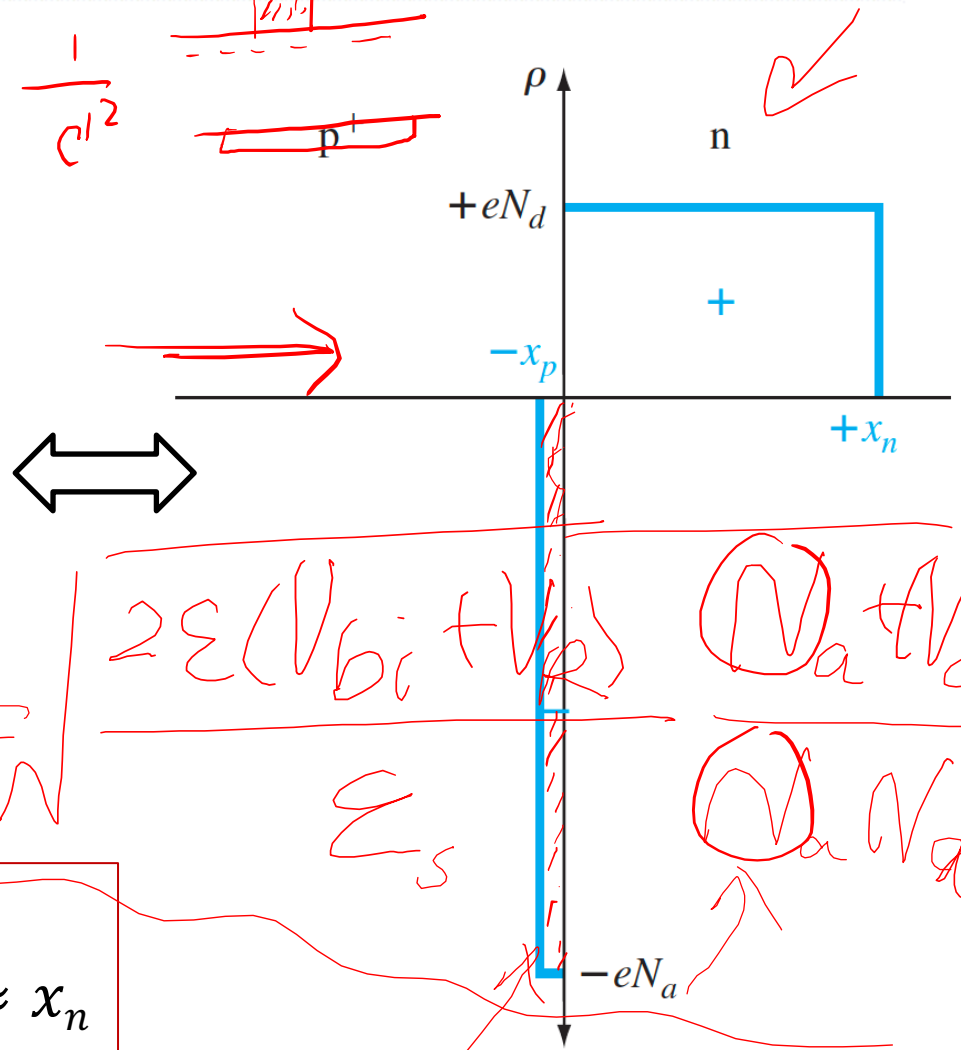
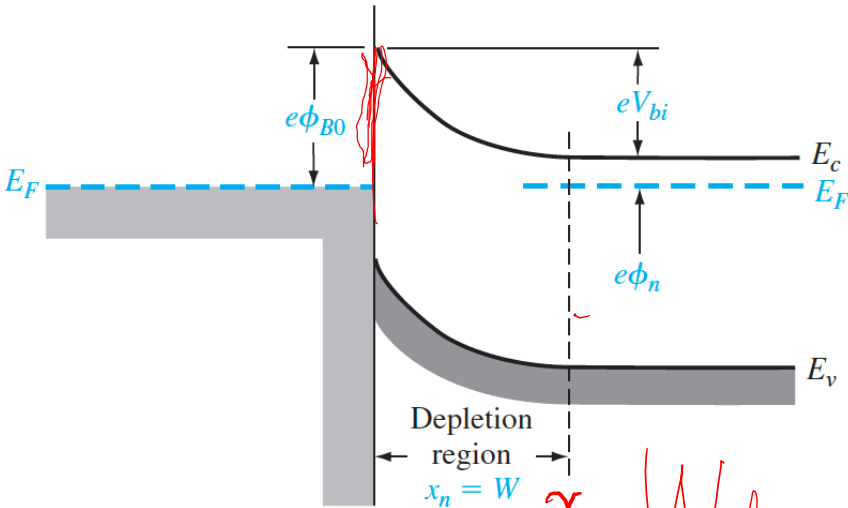
$$E = - \frac{dV(x)}{dx} \quad n \approx N_d$$

$$E = - \frac{eV_d}{\epsilon_s} (x_n - x)$$



# 9.1 The Schottky barrier diode

## Ideal junction properties



$$W = \sqrt{\frac{2\epsilon(V_{bi} + V_R)}{q} \frac{1}{N_d}} \approx x_n$$

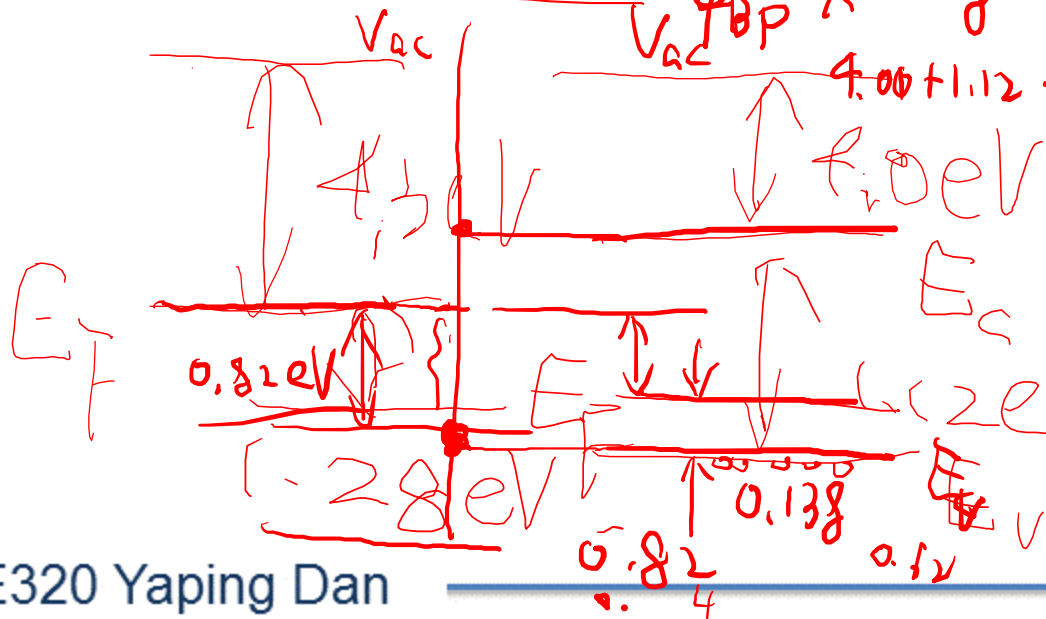
# Check your understanding

## Problem example #1

A metal-semiconductor junction is formed between a metal with a work function of 4.3 eV and p-type silicon with an electron affinity of 4.0 eV. The acceptor doping concentration in the silicon is  $N_a = 5 \times 10^{16} \text{ cm}^{-3}$ . Assume  $T = 300\text{K}$ . (a) Sketch the energy-band diagram. (b) Determine the height of the Schottky barrier. (c) Sketch the energy-band diagram with an applied reverse-biased voltage of  $V_R = 3\text{V}$ . (d) Sketch the energy-band diagram with applied forward-bias voltage of  $V_a = 0.25\text{V}$ .

$$p_0 = N_v \exp\left(-\frac{E_F + E_v}{kT}\right)$$

(a)

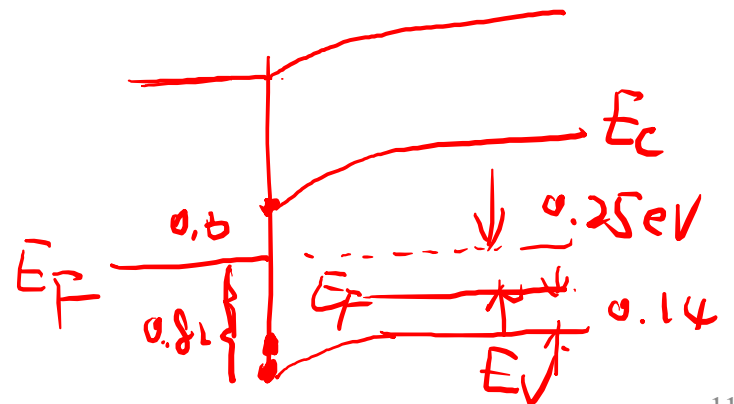
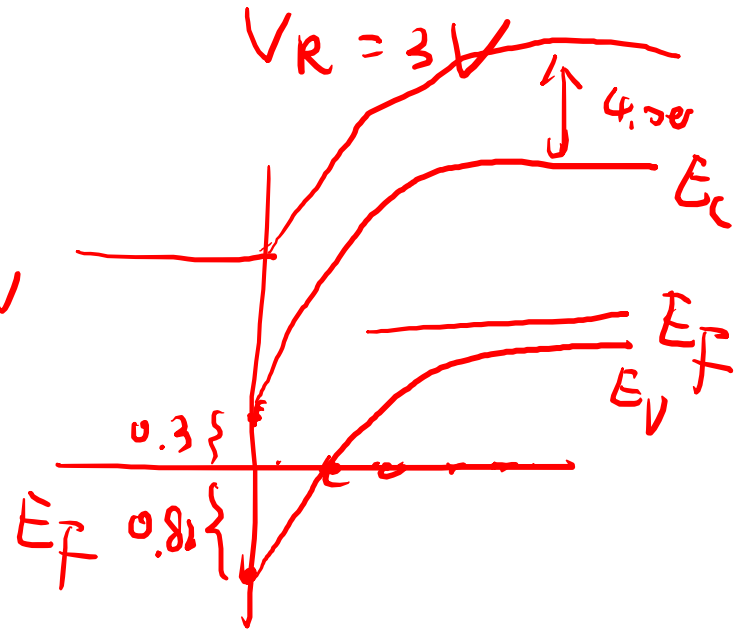
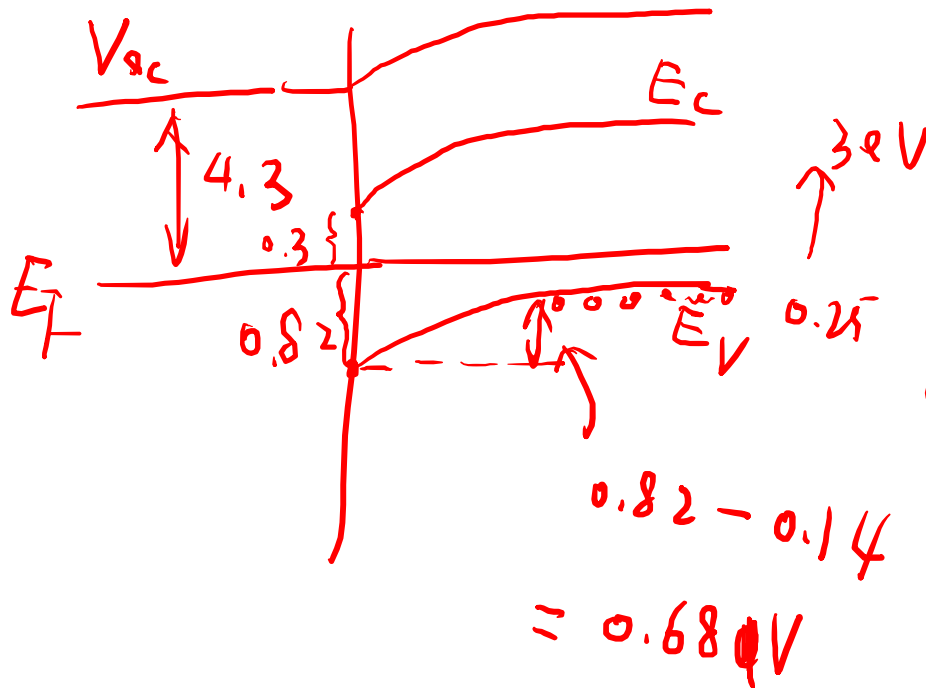


$$\phi_B = \chi + E_g - \phi_m = 4.00 + 1.12 - 4.3 = 0.82 \text{ eV}$$

$$E_F = E_v + kT \ln \frac{N_a}{N_v} = E_v + 0.138 \text{ eV} = 2.88 + 0.138 = 3.02 \text{ eV}$$

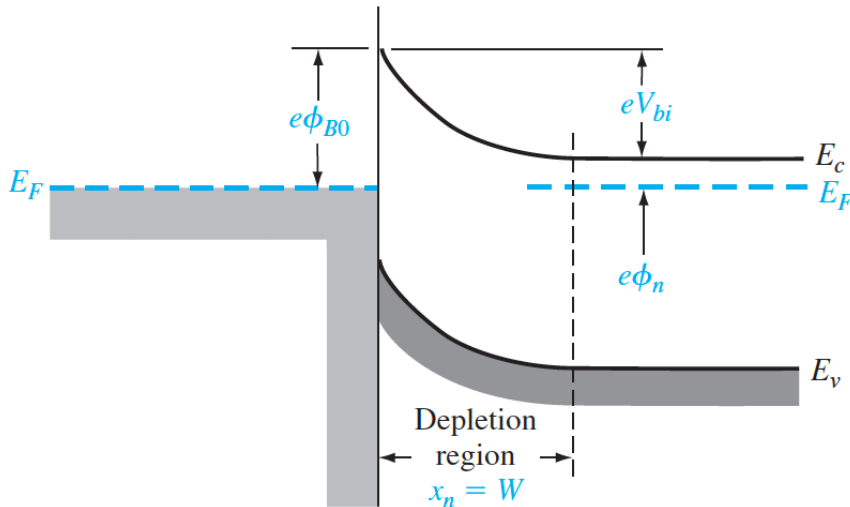
# Check your understanding

## Problem example #1



# 9.1 The Schottky barrier diode

## Ideal junction properties (capacitance)



$$C = \left. \frac{dQ}{dV_b} \right|_{V_b = V_R} = \frac{\epsilon}{W_{dep}}$$

$$= \sqrt{\frac{q \epsilon N_d}{2(V_{bi} + V_R)}}$$

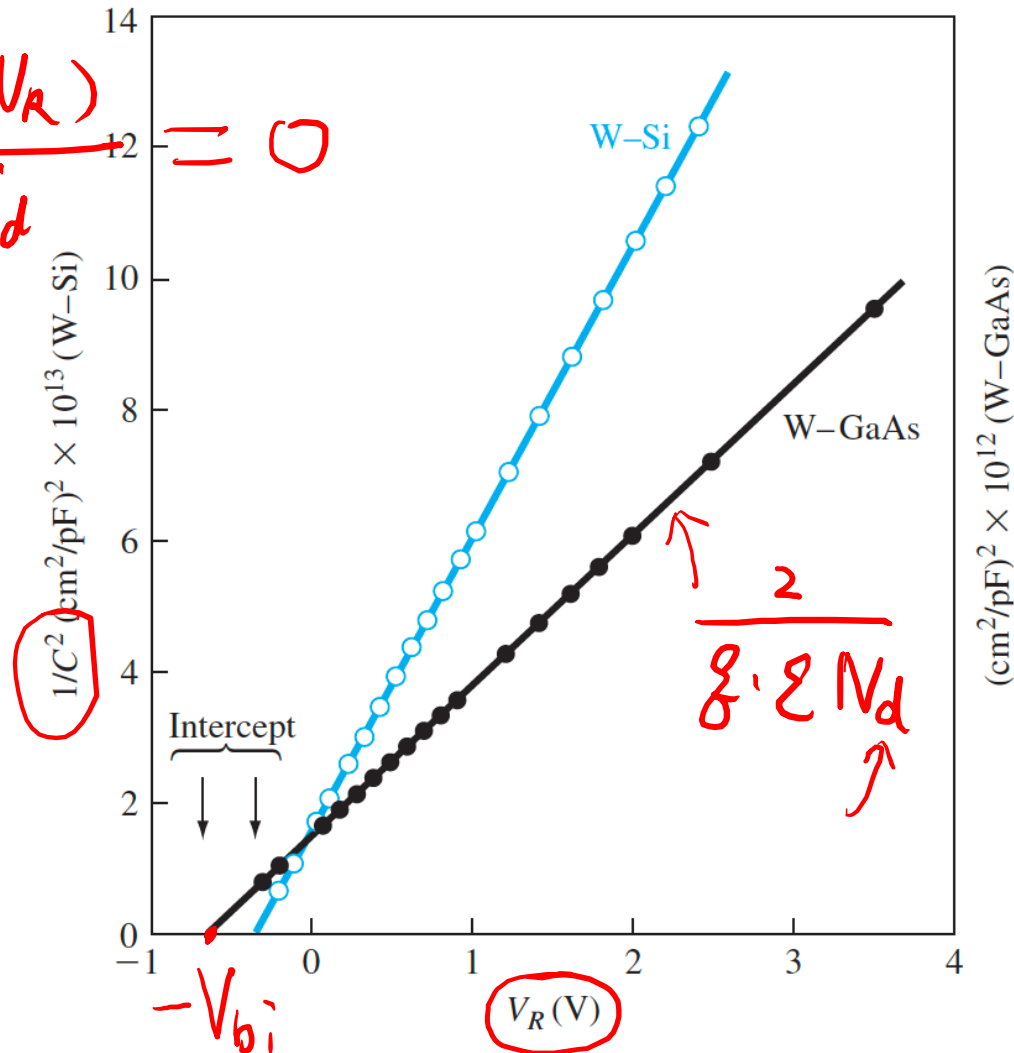
$$W_{dep} = \sqrt{\frac{2 \epsilon (V_{bi} + V_R)}{q N_d}}$$

$$\frac{1}{C^2} = \frac{2(V_{bi} + V_R)}{q \epsilon N_d}$$

# 9.1 The Schottky barrier diode

## Ideal junction properties

$$\frac{1}{C^2} = \frac{2(V_{bi} + V_R)}{q\epsilon N_d} = \square$$



# 9.1 The Schottky barrier diode

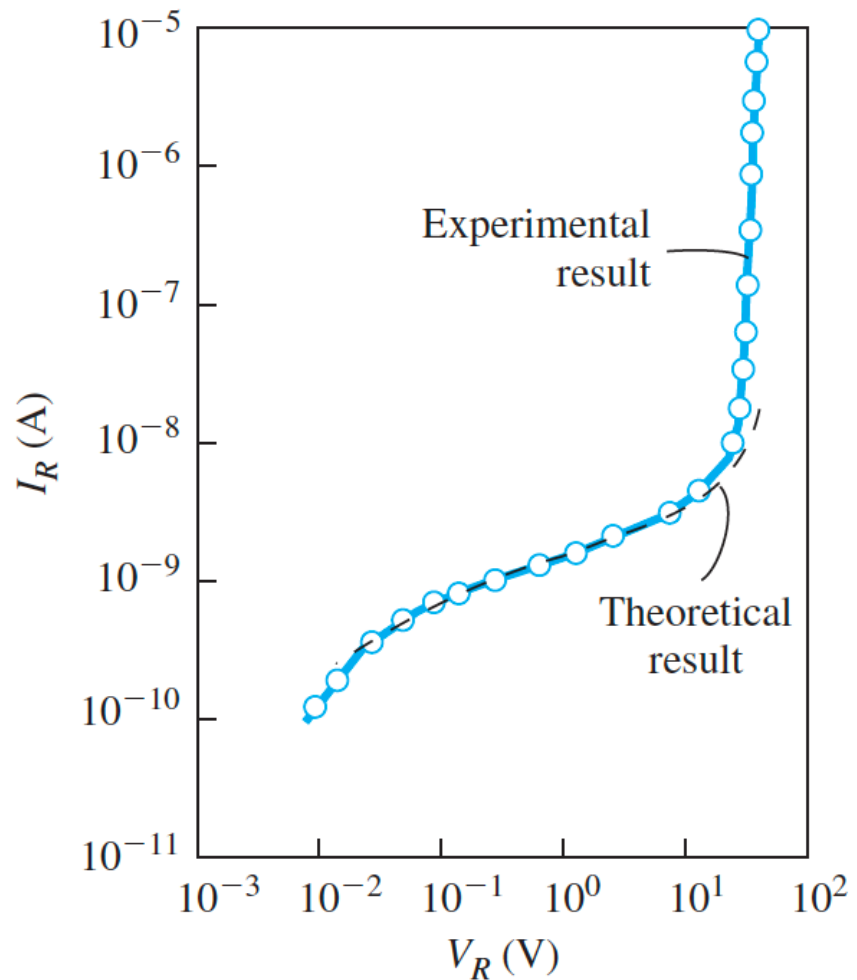
## Current-voltage relationship

$$J = J_{sT} \left[ \exp \left( \frac{eV_a}{kT} \right) - 1 \right]$$

$$J_{sT} = A^* T^2 \exp \left( \frac{-e\phi_{Bn}}{kT} \right)$$

$$A^* \equiv \frac{4\pi e m_n^* k^2}{h^3}$$

Richardson constant



$$J_{sT} = A^* T^2 \exp \left( \frac{-e\phi_{B0}}{kT} \right) \exp \left( \frac{e\Delta\phi}{kT} \right)$$

# 9.1 The Schottky barrier diode

## Compare Schottky diode and PN junction

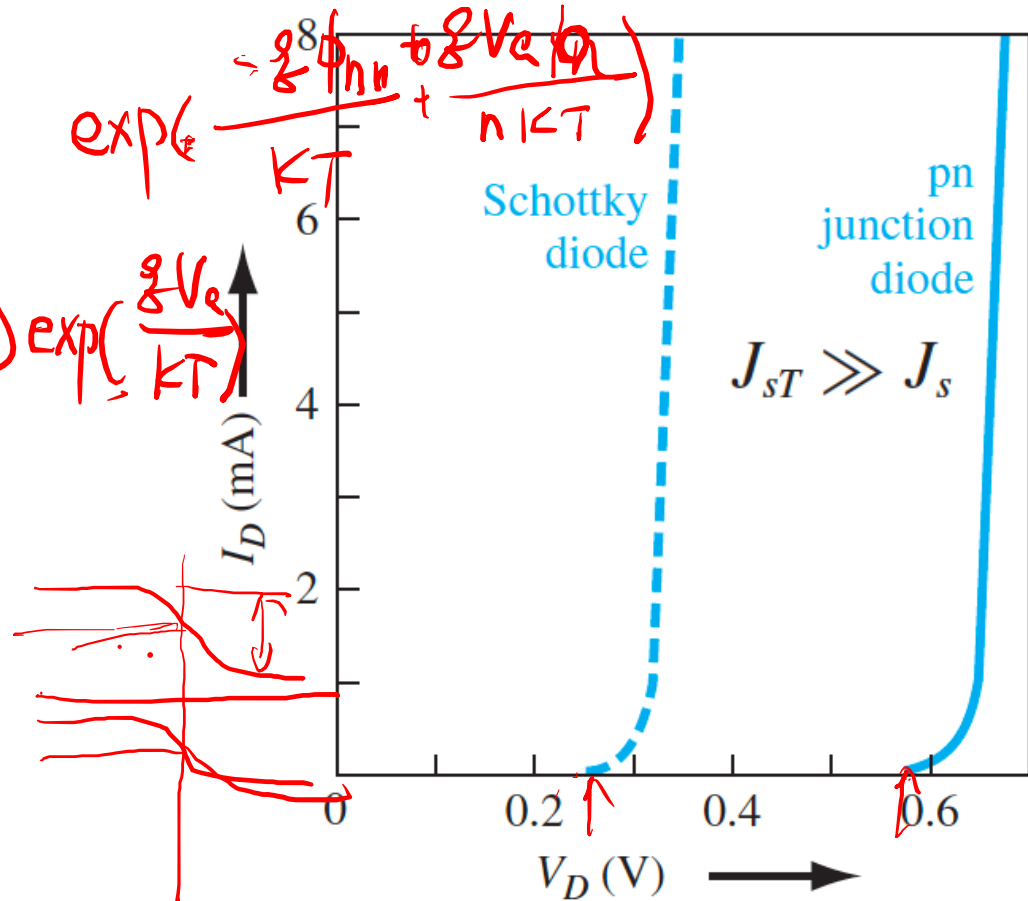
$$J = J_{sT} \left[ \exp\left(\frac{eV_a}{kT}\right) - 1 \right]$$

$$I = A_c A^* T^2 \exp\left(\frac{-e\phi_{Bn}}{kT}\right) \exp\left(\frac{eV_a}{kT}\right)$$

$$J_{sT} = A^* T^2 \exp\left(\frac{-e\phi_{Bn}}{kT}\right)$$

$$A^* \equiv \frac{4\pi e m_n^* k^2}{h^3}$$

Richardson constant



$$J_s = \frac{eD_n n_{po}}{L_n} + \frac{eD_p p_{no}}{L_p}$$

# Check your understanding

## Problem example #2

*n-type*

Consider a tungsten barrier on silicon with a measured barrier height of  $\phi_{Bn} = 0.67\text{eV}$ .  
The effective Richardson constant is  $A^* = 114 \text{ A/K}^2\text{cm}^2$ .  $T = 300\text{K}$ .

$$J_{ST} = A^* T^2 \exp\left(-\frac{q\phi_{Bn}}{kT}\right)$$

$V_a = 0.1\text{V}$

$$114 \times (300)^2 \exp\left(-\frac{0.67}{0.0259}\right)$$

$$= 5.98 \times 10^5 \text{ A/cm}^2$$

$$J = J_{ST} \left[ \exp\left(\frac{qV_a}{kT}\right) - 1 \right] = 5.98 \times 10^5 \left( e^{0.0259} - 1 \right)$$



# Check your understanding

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$$\begin{aligned} J &= J_{ST} \left( e^{\frac{qV_a}{kT}} - 1 \right) \\ &= 5.98 \times 10^5 \left[ e^{\frac{0.1}{0.0259}} - 1 \right] \\ &= 5.98 \times 10^5 (46.5 - 1) \\ &= 2.72 \times 10^7 \text{ A/cm}^2 \end{aligned}$$

# Check your understanding

## Problem example #3

### **Control of the Schottky Barrier Height in Monolayer WS<sub>2</sub> FETs using Molecular Doping**

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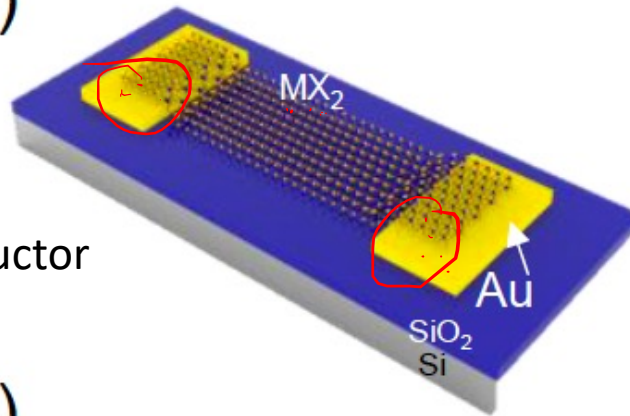
# Check your understanding

## Problem example #3

$$I_{sd} = AA_{2D}^* T^{3/2} \exp \left[ -\frac{q}{k_B T} \left( \Phi_B - \frac{V_{ds}}{n} \right) \right]$$

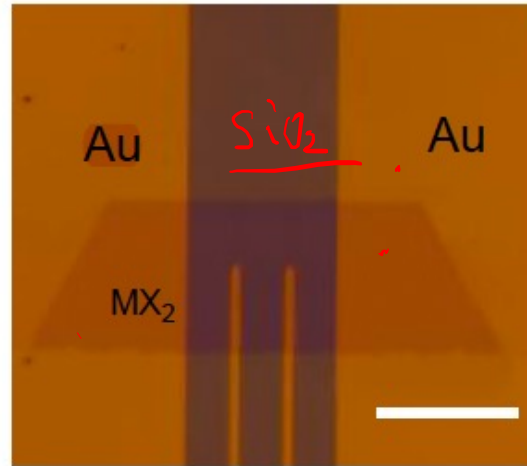
ideality

(a)



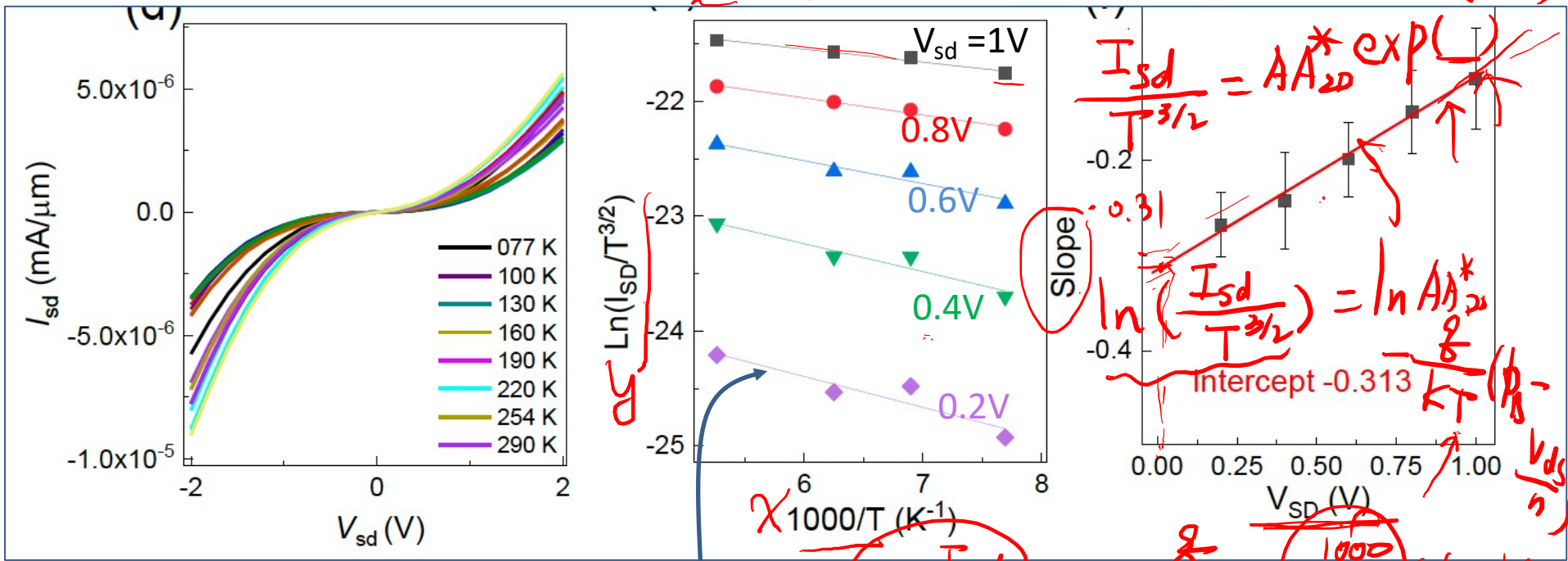
WS<sub>2</sub> atomically thin  
monolayer semiconductor

(b)



# Check your understanding

## Problem example #3



- 1) Write the analytical expression of Line 1 if we take  $1000/T$  as  $x$  and  $\ln(I_{sd}/T^{2/3})$  as  $y$ ?
- 2) Write the expression of Slope in the right figure.
- 3) Find Schottky barrier height  $\Phi_B$ .

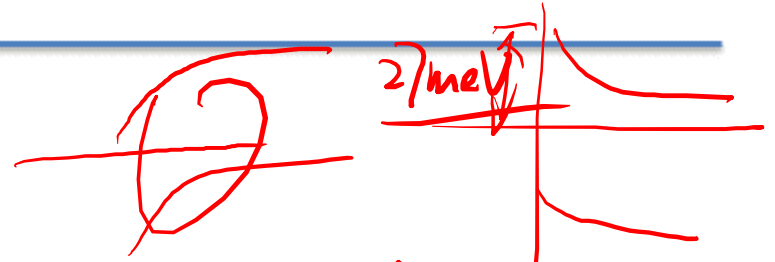
Handwritten solutions:

$$y' = -\frac{q}{1000k_B} \left(\Phi_B - \frac{x}{n}\right) \Rightarrow y' = -\frac{q}{1000k_B} \left(\Phi_B - \frac{V_{ds}}{n}\right)$$

$$y = -\frac{q}{1000k_B} \left(\Phi_B - \frac{V_{ds}}{n}\right) \cdot x$$

# Check your understanding

## Problem example #3



$$\ln \left( \frac{I_{sd}}{T^{3/2}} \right) = \ln (A \cdot A_{2D}^*) - \frac{q}{1000 k_B} \left( \phi - \frac{V_{ds}}{n} \right) \cdot \frac{1000}{T}$$

$$y = \ln (A \cdot A_{2D}^*) - \frac{q}{1000 k_B} \left( \phi - \frac{V_{ds}}{n} \right) x$$

$$y = \text{slope} = - \frac{q}{1000 k_B} \left( \phi_{Bn} - \frac{V_{ds}}{n} \right)$$

$$y' = - \frac{q}{1000 k_B} \left( \phi_{Bn} - \frac{x'}{n} \right) \quad -0.31 = y_0 = - \frac{q}{1000 k_B} \phi_{Bn}$$

$$\phi_{Bn} = 27 \text{ meV}$$

# Outline

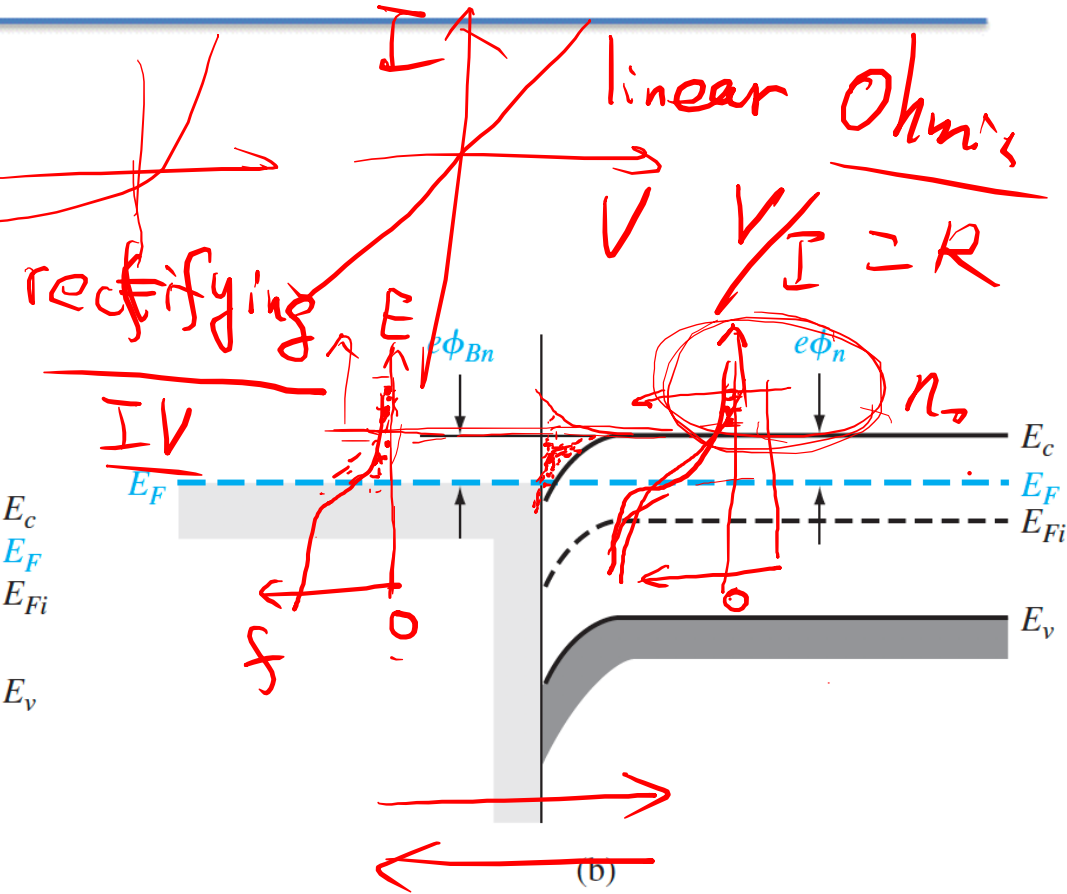
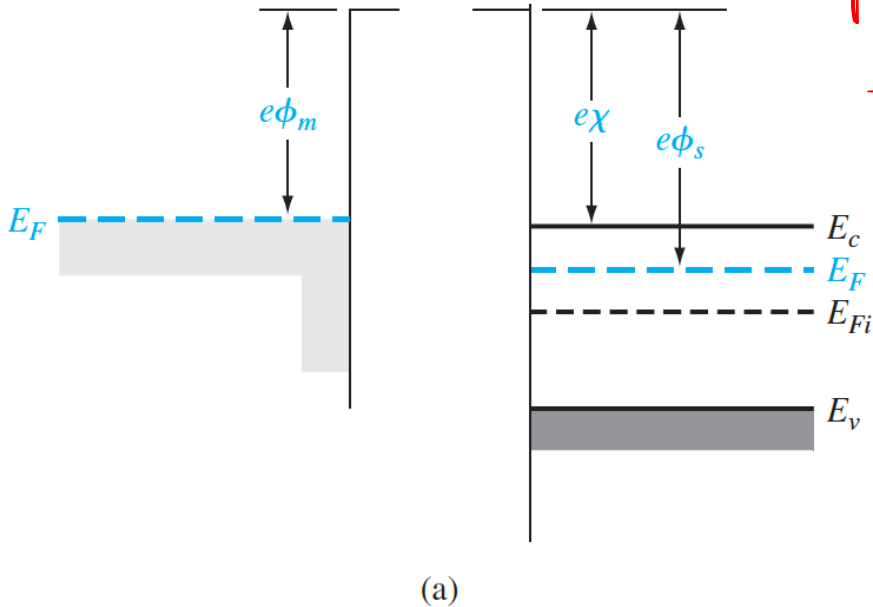
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9.1 The Schottky barrier diode

**9.2 Metal-semiconductor Ohmic contacts**

## 9.2 Metal-semiconductor Ohmic contacts

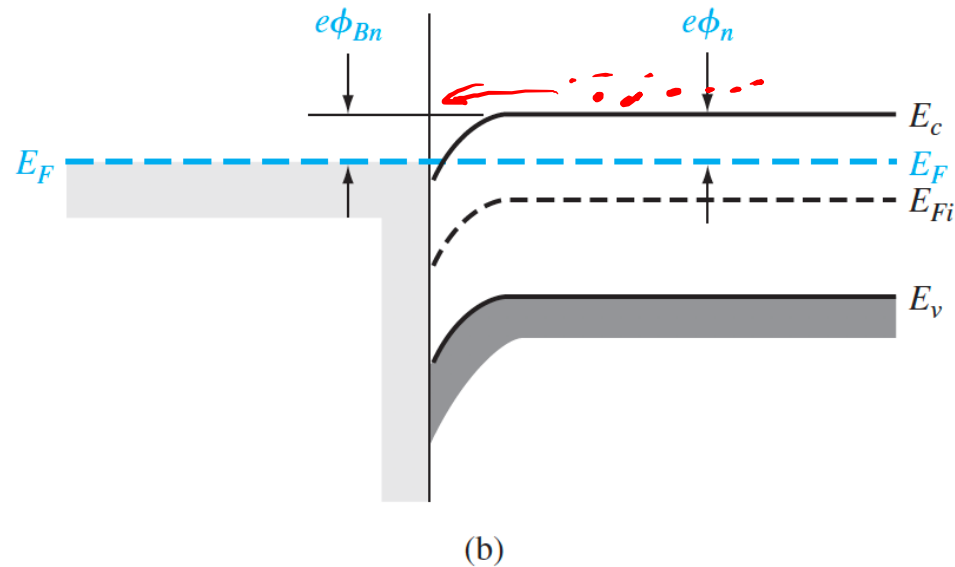
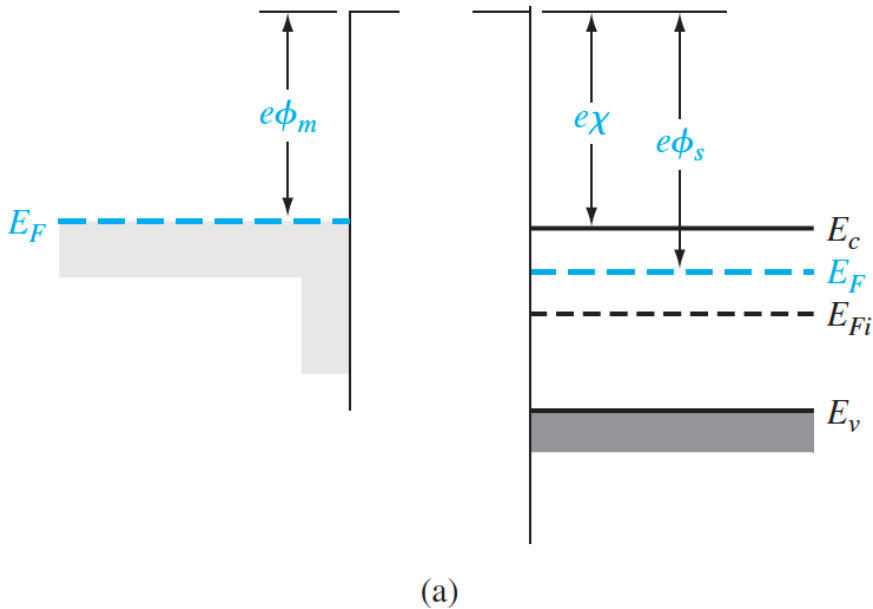
### Ideal Nonrectifying Barrier



## 9.2 Metal-semiconductor Ohmic contacts

### Ideal Nonrectifying Barrier

*n-type  $W_s \geq W_m \Rightarrow \text{ohmic}$*

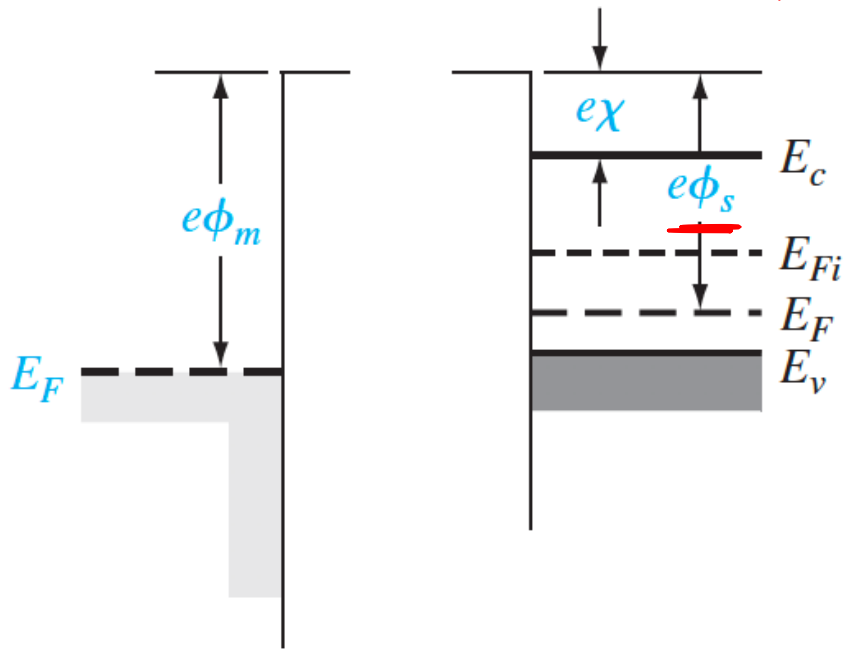




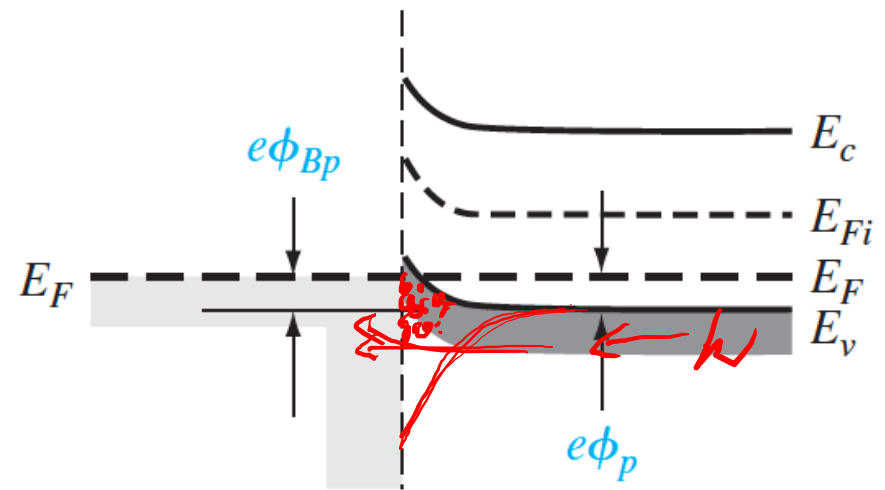
# 9.2 Metal-semiconductor Ohmic contacts

## Ideal Nonrectifying Barrier

*p-type*  $W_s \leq W_m$   
 $e\phi_s \leq e\phi_m$

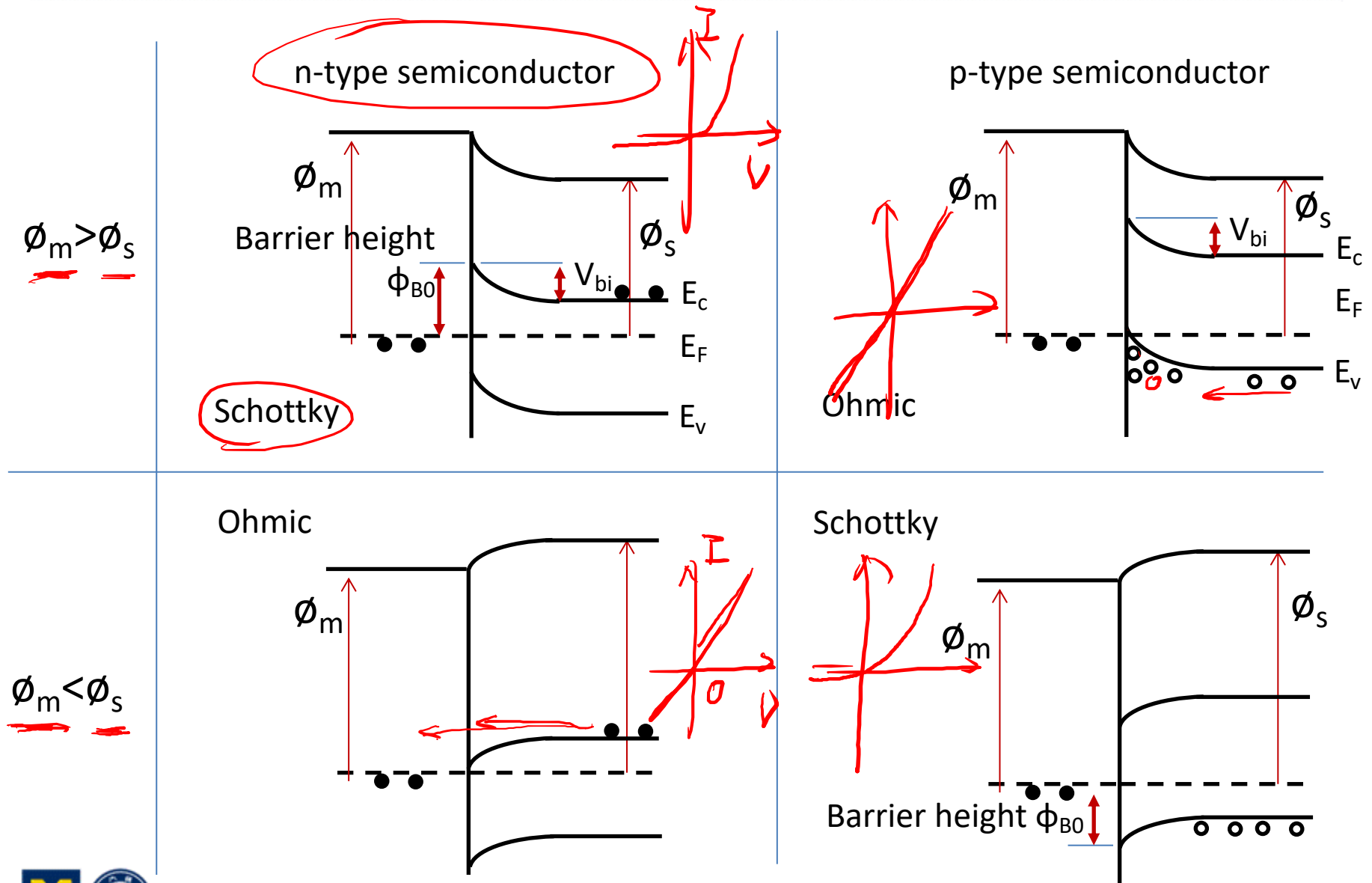


(a)



(b)

## 9.2 Metal-semiconductor Ohmic contacts



# Check your understanding

## Problem example #4

For Si, if it is doped with phosphorus at a concentration of  $10^{15} \text{ cm}^{-3}$ , what metal you can choose from the list for Ohmic contact. *n-type*  
*Ag Au*

Repeat the question above for p-type Si doping at the concentration of  $10^{17} \text{ cm}^{-3}$ .  
Si has an electron affinity of  $4.01 \text{ eV}$  and a bandgap of  $1.12 \text{ eV}$ . *(Au, Ni, Pd, Pt)*

**Table 9.1** | Work functions of some elements

Element	Work function, $\phi_m$
Ag, silver	4.26
Al, aluminum	4.28
Au, gold	5.1
Cr, chromium	4.5
Mo, molybdenum	4.6
Ni, nickel	5.15
Pd, palladium	5.12
Pt, platinum	5.65
Ti, titanium	4.33
W, tungsten	4.55

$$n_0 = N_c \exp\left(\frac{E_F - E_c}{kT}\right) \Rightarrow E_F - E_c = kT \ln \frac{n_0}{N_c} = 0.0259 \times \ln \frac{10^{15}}{2.8 \times 10^{19}} = -0.265 \text{ eV}$$

$$E_F = E_c - 0.265 \text{ eV} = -4.01 \text{ eV} - 0.265 \text{ eV} = -4.275 \text{ eV}$$

$$\phi_s = 4.275 \text{ eV}$$

*Diagram: Energy level diagram for Si. The conduction band edge  $E_c$  is at  $-4.01 \text{ eV}$ . The Fermi level  $E_F$  is at  $-4.275 \text{ eV}$ . The valence band edge  $E_v$  is at  $-5.13 \text{ eV}$ . The electron affinity  $\chi$  is  $0.265 \text{ eV}$ . The work function  $\phi_s$  is  $4.275 \text{ eV}$ . The condition  $\phi_s > \phi_m$  is indicated.*

# Check your understanding

## Problem example #4

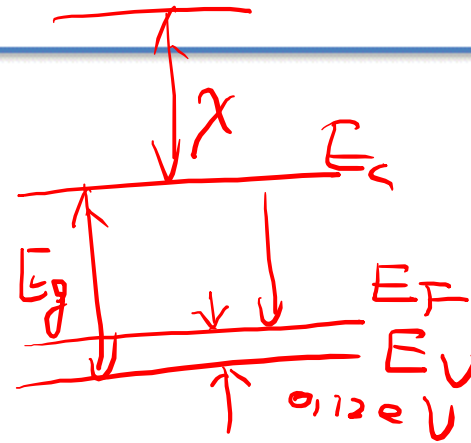
$$P_o = N_o \exp\left(\frac{E_v - E_F}{kT}\right)$$

$$\frac{P_o}{N_c} = \exp\left(\frac{E_v - E_F}{kT}\right)$$

$$\ln \frac{P_o}{N_c} = \frac{E_v - E_F}{kT}$$

$$kT \ln \frac{P_o}{N_c} = E_v - E_F$$

$$E_F = E_v - kT \ln \frac{P_o}{N_c} = E_v + 0.12 \text{ eV}$$



$$E_F = -5.13 + 0.12 \text{ eV} \\ = -5.01 \text{ eV}$$

$$E_v = -\chi - E_g$$

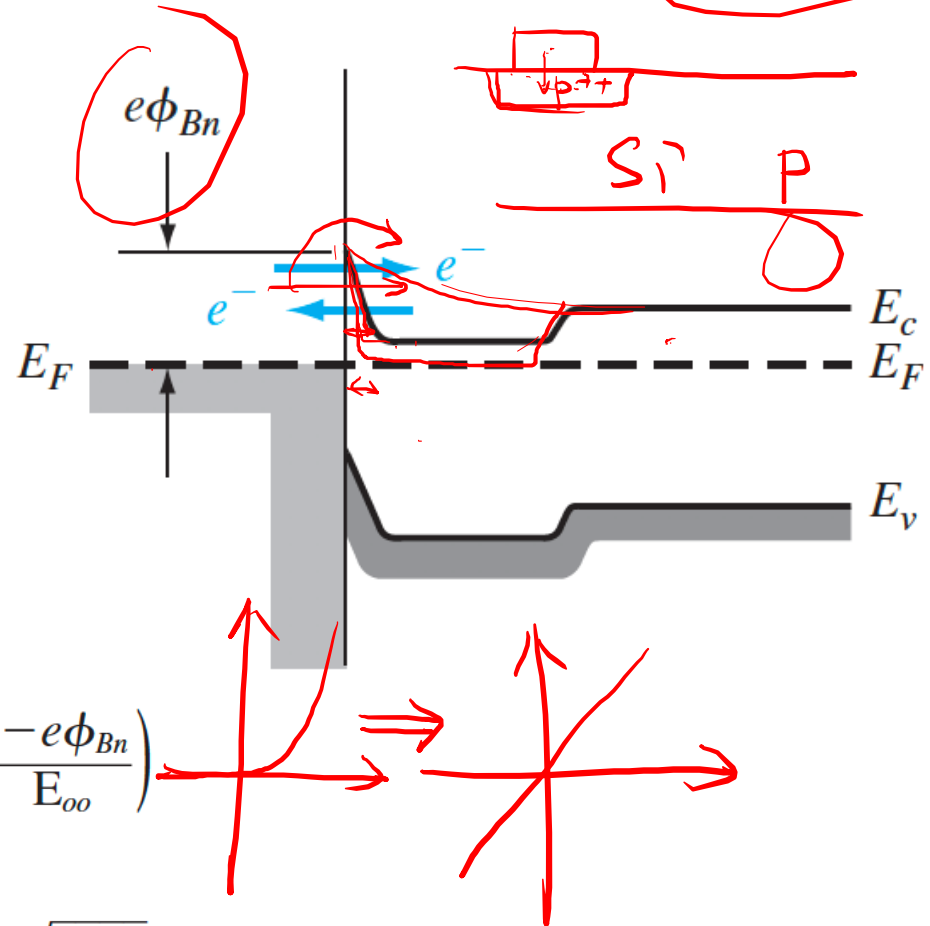
$$\phi_s = 5.01 \text{ eV} = -4.01 - 1.12 \\ = -5.13 \text{ eV}$$

$$\boxed{\phi_s \leq \phi_m} \text{ for ohmic}$$

## 9.2 Metal-semiconductor Ohmic contacts

VE312

### 1. Tunneling Barrier



The tunneling current has the form

$$J_t \propto \exp\left(\frac{-e\phi_{Bn}}{E_{oo}}\right)$$

where

$$E_{oo} = \frac{e\hbar}{2} \sqrt{\frac{N_d}{\epsilon_s m_n^*}}$$

The tunneling current increases exponentially with doping concentration.

## 9.2 Metal-semiconductor Ohmic contacts

### 2.Silicide alloy

Nickel silicide, NiSi

Titanium silicide, TiSi<sub>2</sub>

